

FIG. 1

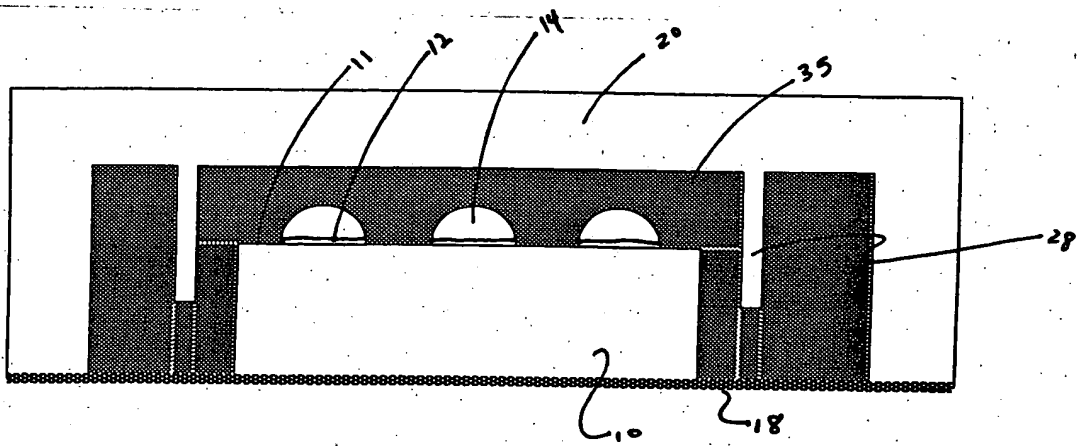


FIG. 3

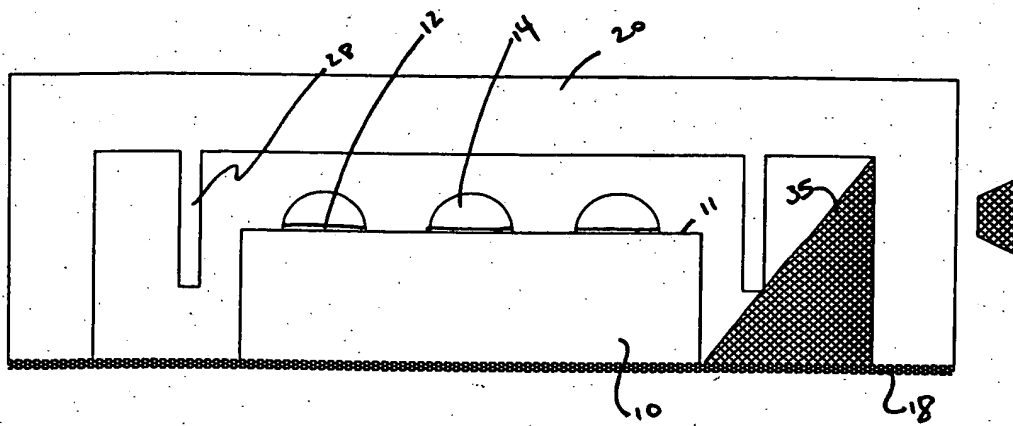


FIG. 2

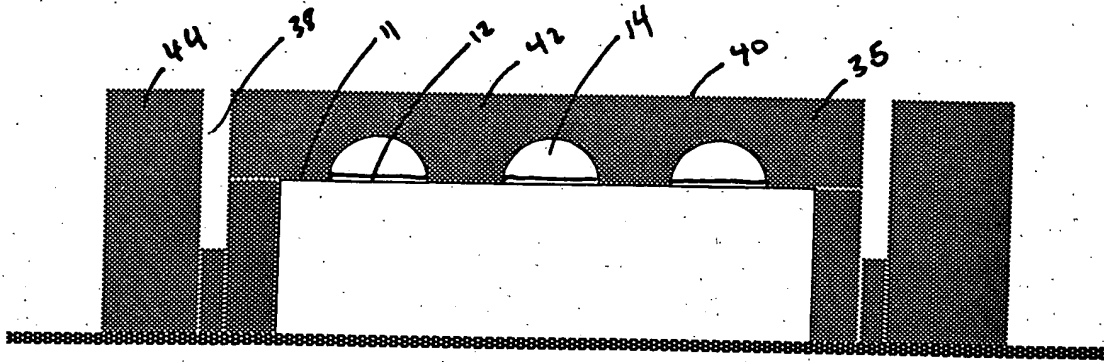


FIG. 4

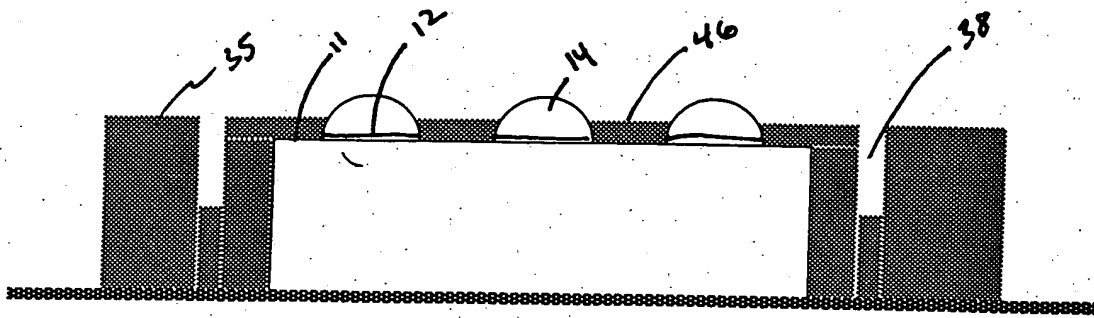


FIG. 5

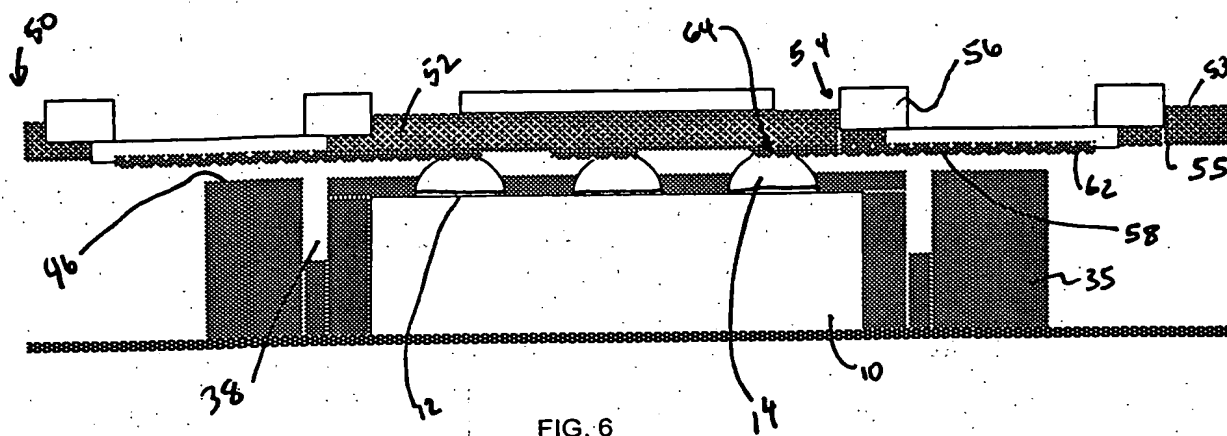


FIG. 6

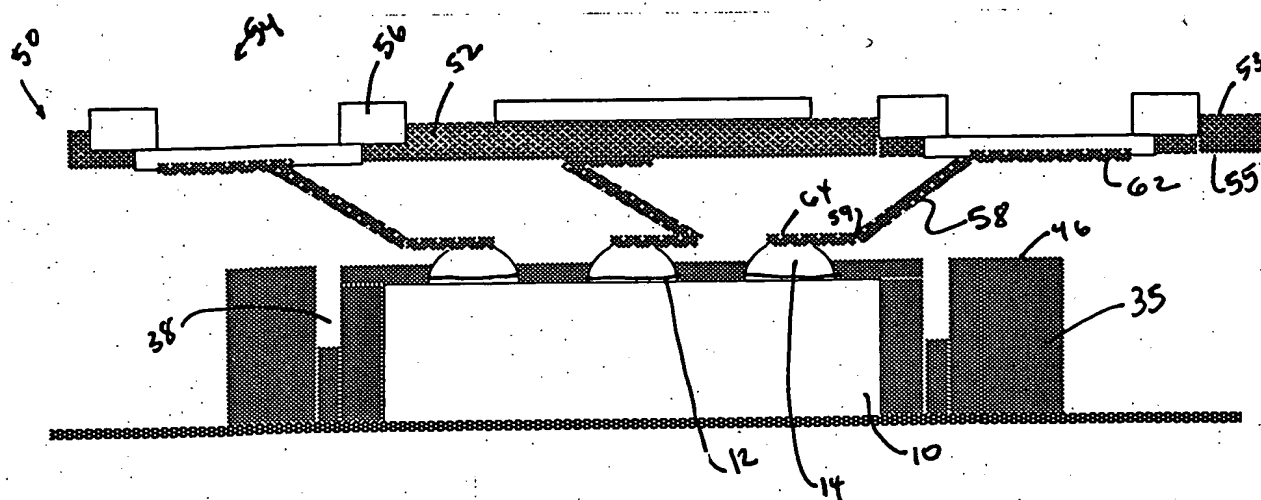


FIG. 7

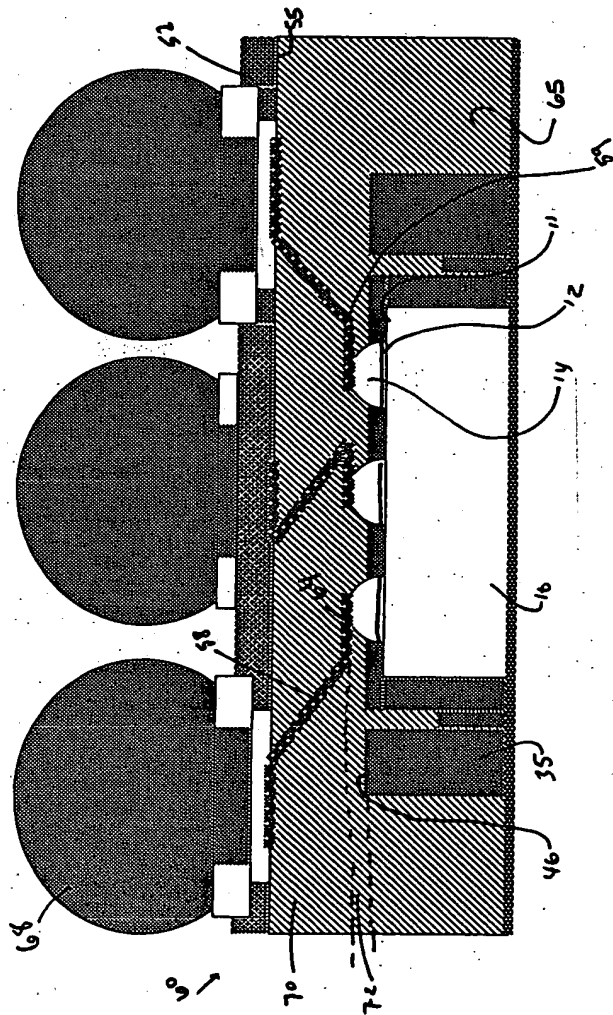


FIG. 8A

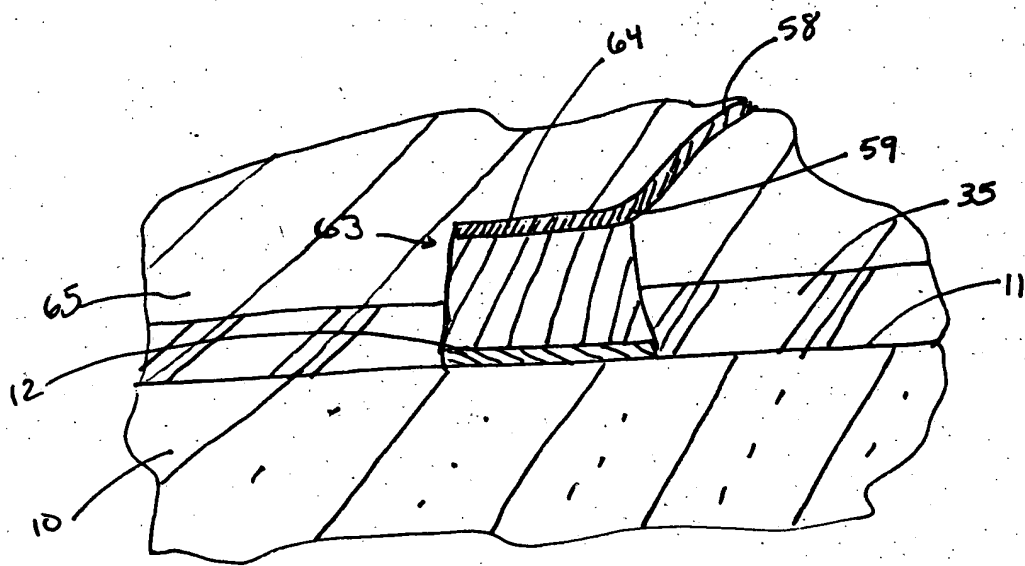


FIG. 8B

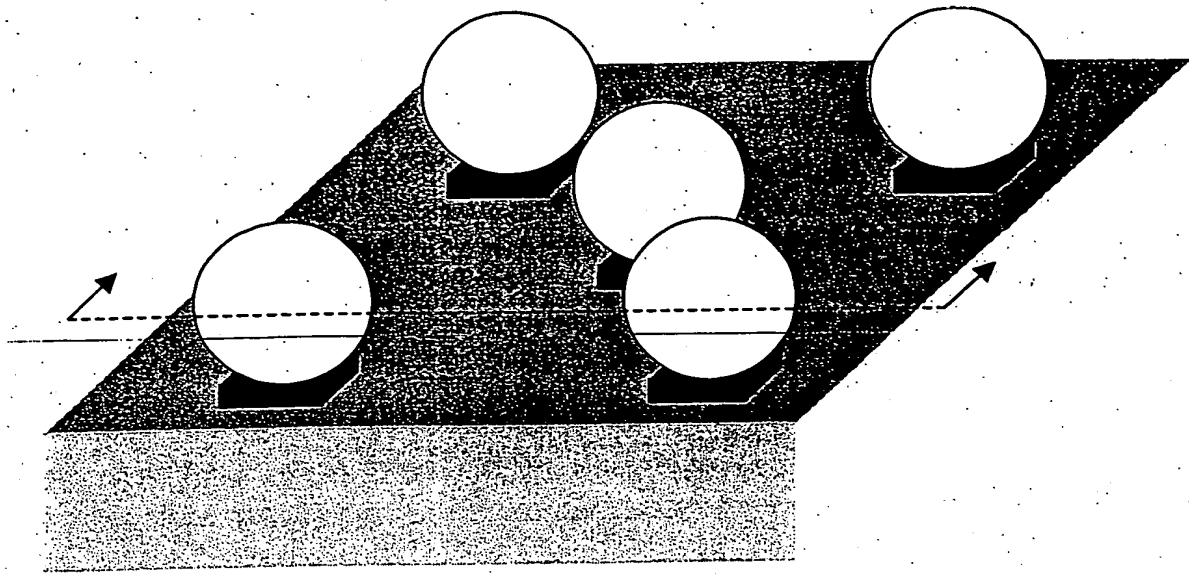


FIG. 9

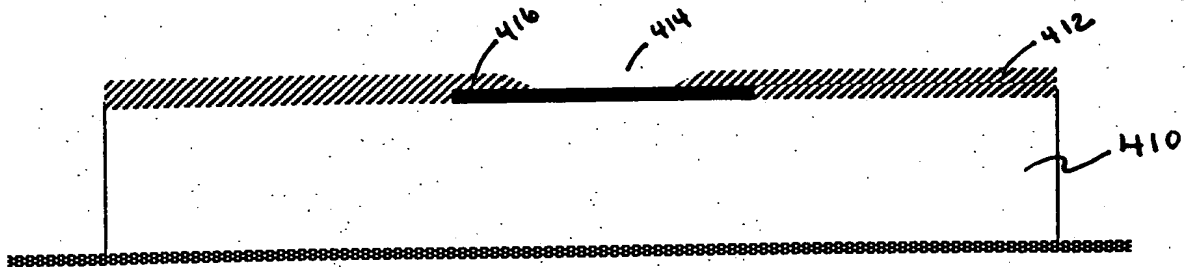


FIG. 17

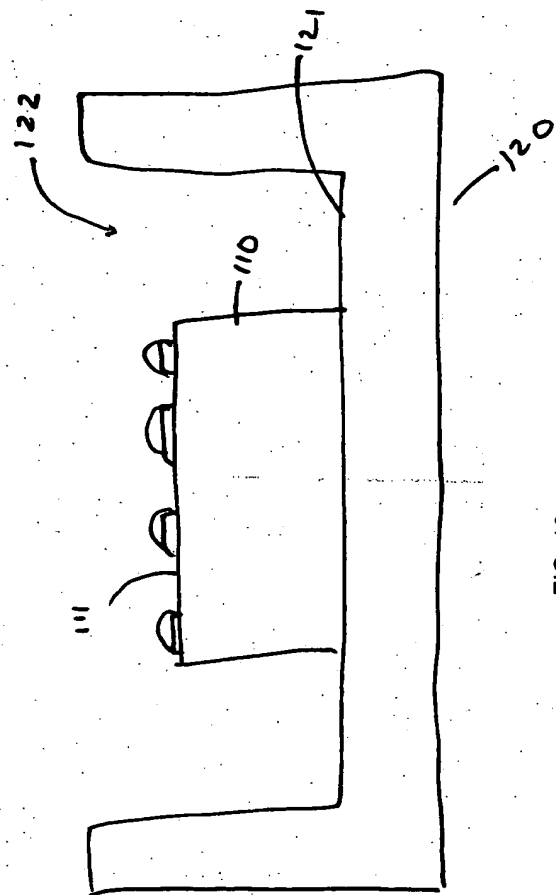


FIG. 10



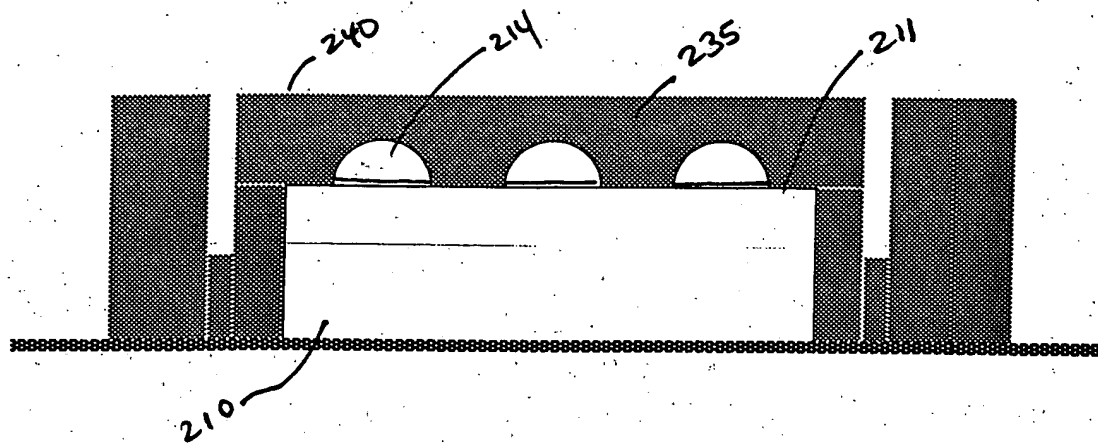


FIG. 11

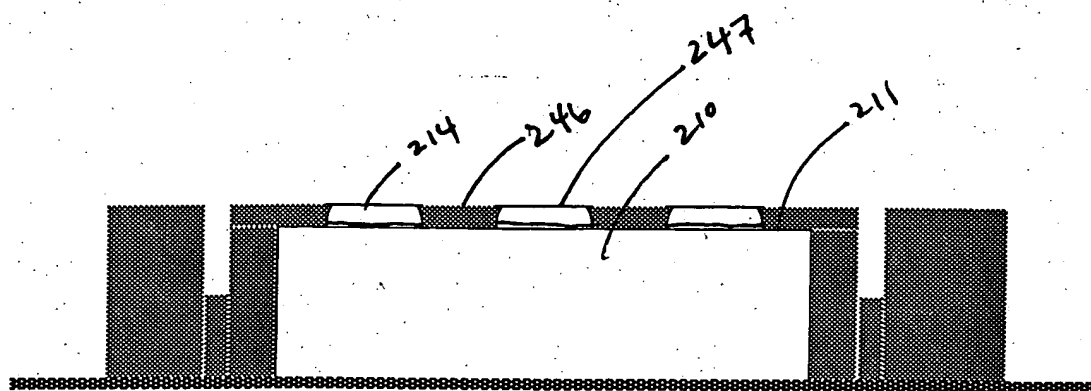


FIG. 12

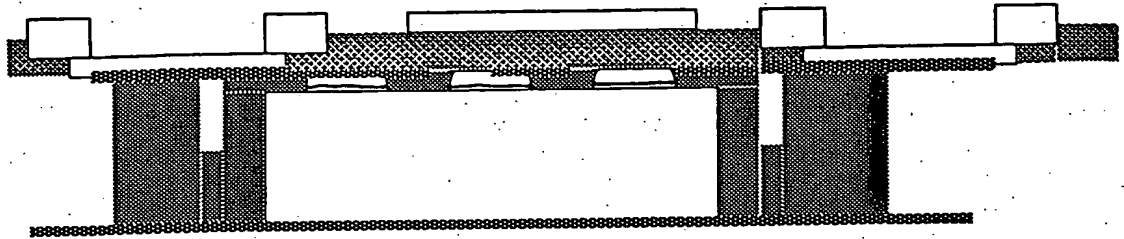


FIG. 13

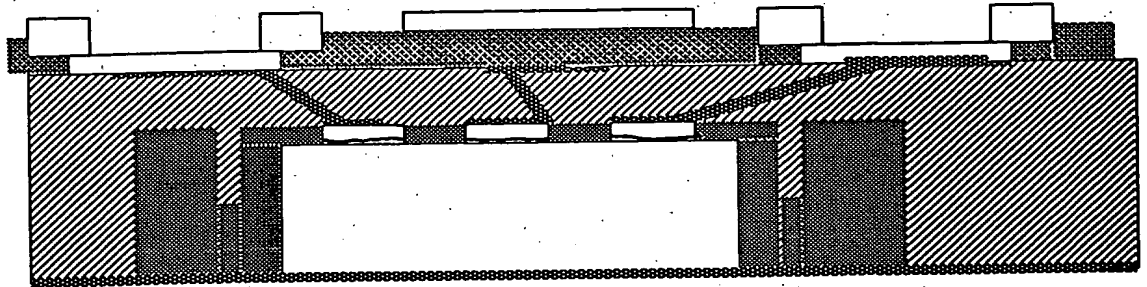


FIG. 14

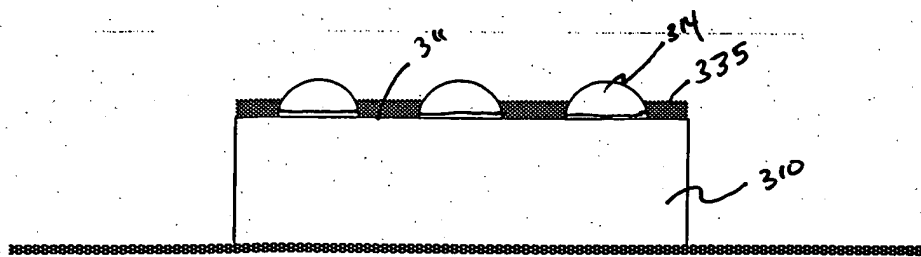


FIG. 15

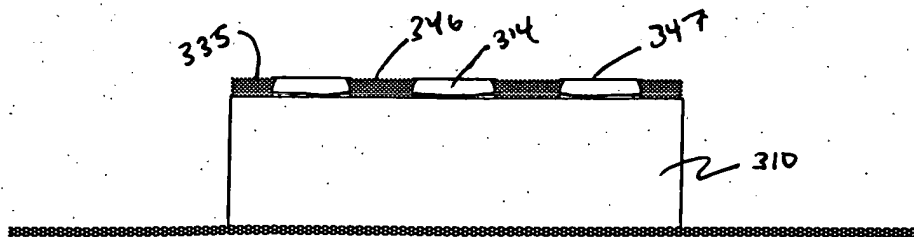


FIG. 16

A cross-sectional view of a device. A substrate 410 is shown at the bottom. A layer 412 is on top of the substrate. A wavy layer 416 is on top of layer 412. A layer 420 is on top of layer 416. A layer 422 is on top of layer 420. A layer 424 is on top of layer 422. A layer 426 is on top of layer 424. A layer 418 is on top of layer 426. A layer 420 is on top of layer 418. A layer 412 is on top of layer 420. A layer 410 is on top of layer 412.

FIG. 19.

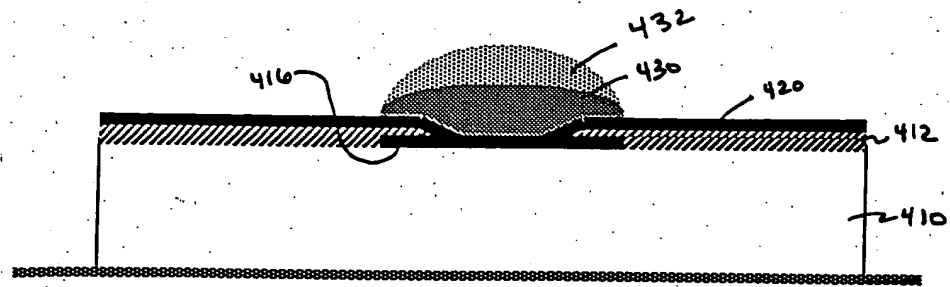


FIG. 20

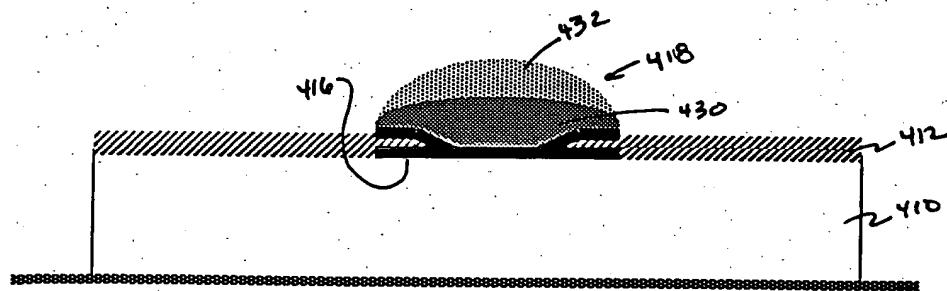
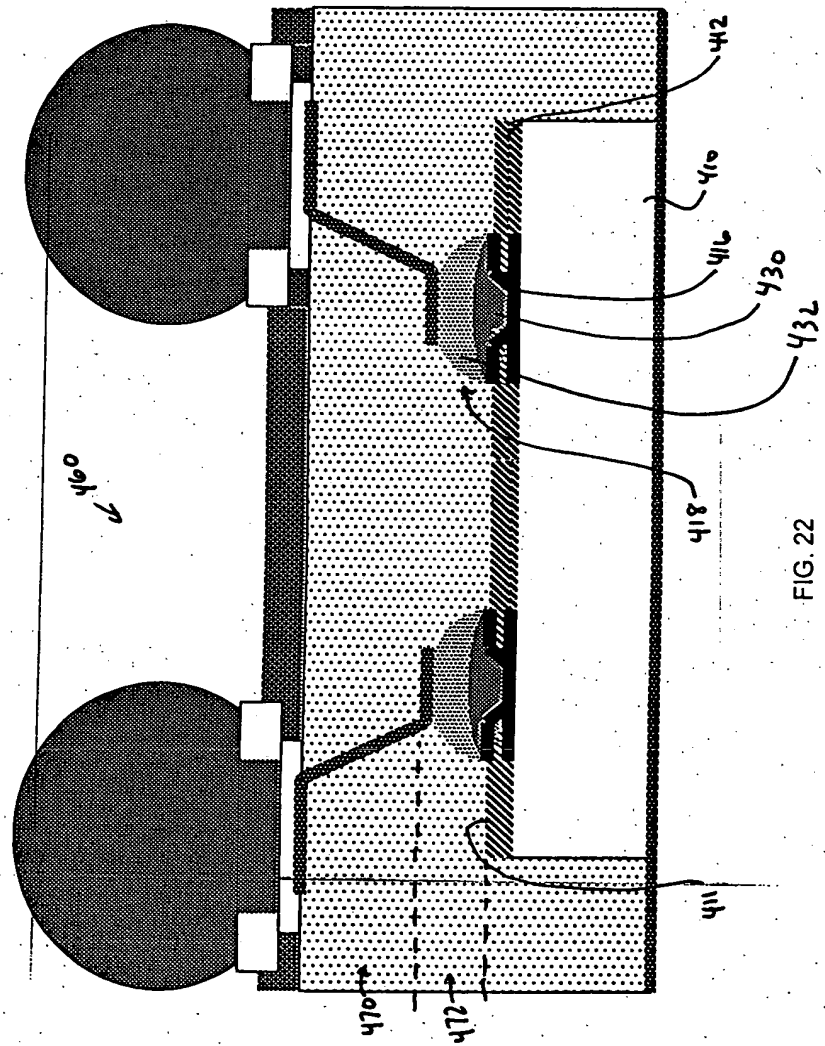


FIG. 21



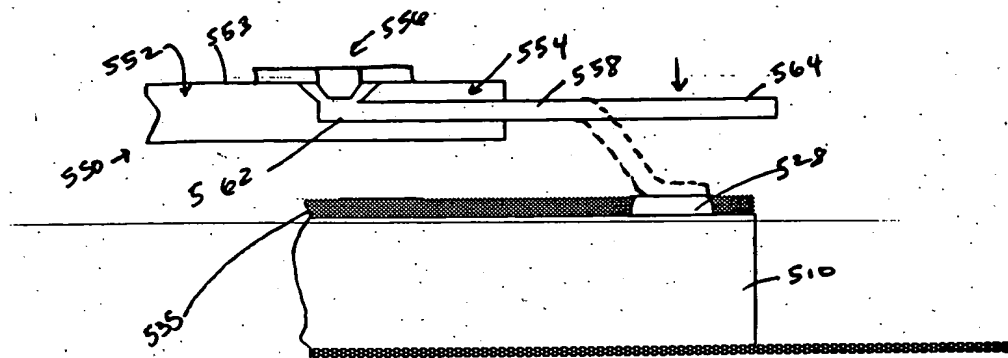


FIG. 23

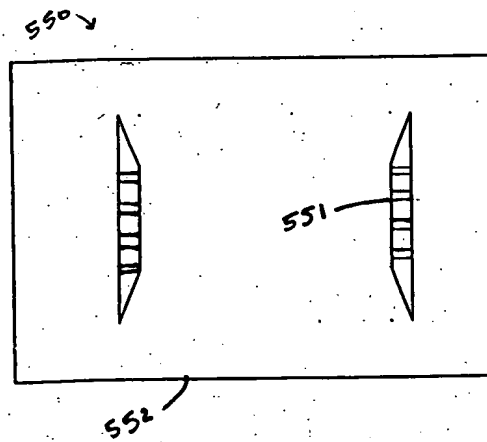


FIG. 24